DENNIS RICH

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EDUCATION

Stanford University

Ph.D - ELECTRICAL ENGINEERING

GPA: 3.97/4.0 Expected June 2024

GPA: 4.0/4.0

University of Illinois at Urbana-Champaign

DUAL B.S. - ELECTRICAL ENGINEERING AND ENGINEERING PHYSICS

Conferred May 2019 with Highest Honors

RESEARCH EXPERIENCE

Robust Systems Group

Stanford University, May 2019 - Present

- Automated IC power and thermal analysis flow with McPAT, 3D-ICE, COMSOL, Cadence Celsius, Python, and more
- Developed new physical design methods leading to over 50% 3DIC junction temperature reduction
- Performed LabView workbench IC characterization of 1.4Mb phase-change memory arrays to investigate new write strategies

Innovative Compound Semiconductor Lab

University of Illinois, October 2015 - March 2019

- Led lab members to develop new CMOS fabrication processes
- Programmed MATLAB analysis tool with user interface for theoretical stress-induced cracking calculations
- Fabricated and characterized semiconductor devices with e-beam, profilometry, and more in cleanroom environment

Silicon Labs, Inc.

Nashua, NH (Timing Division), May 2017 - August 2017

- Designed new splitting techniques for preserving signal integrity in PCB-based transmission lines
- Analyzed and diagnosed circuitry and layout deficiencies in phase-locked loop designs

Patankar Research Group

Northwestern University, May 2014 - August 2014

• Collected and analyzed molecular data of waterproof system with C++

Mesoscopic Physics Group

Northwestern University, May 2013 - August 2013

• Synthesized and analyzed carbon nanotube MEMS devices with CVD, AFM, and chemical analysis

SKILLS

Software		Laboratory						
Python: pandas, seaborn, multi- Some Tcl, Perl	threading • tcsh • MATLAB •	Fabrication: E-beam, photolithography, masked wet etching, electroplating, mechanical thin-film						
Electronic Systems	Electronic Devices	separation						
Celsius • Virtuoso • McPAT •	COMSOL Heat Transfer	Characterization: Testbench, AFM, SEM,						
Autodesk Inventor	• Lumerical	Profilometry, Raman spectroscopy, Nomarski						
AVAVA DDC AND HONOI	20	microscopy						

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Edward J. McCluskey Graduate Fellowship - Awarded to Ph.D students in computer architectures	2019-2020			
Goldwater Scholarship - Nationally competitive award of \$7,500 per year to 240 promising researchers	2017-2019			
SPIE BACUS Scholarship - \$5,000 awarded to one promising graduate student in optics and photonics	2019			
Bardeen Undergraduate Award - One outstanding senior selected for excellence in semiconductor research	2019			
Robert C. MacClinchie Scholarship - \$30,000 awarded to one senior for leadership and academic merit	2018			
Campus Honors Program Outstanding Senior - Awarded to 16 members of highest honors program at UIUC				
Michael E. Napier Memorial Award - One junior selected annually for excellence while working	2018			

PUBLICATIONS AND PRESENTATIONS.

Published Heterogeneous 3D Nano-systems: The N3XT Approach?

Dennis Rich et. al. in NANO-CHIPS 2030: On-Chip AI for an Efficient Data-Driven World, B. Murmann, Springer (2020)

The Thermodynamics of Restoring Underwater Superhydrophobicity

Paul Jones, Adrian Kirn, Y. David Ma, Dennis Rich, and Neelesh Patankar. Langmuir (2017) 33 (11)

Expected Fixing Monolithic 3D's Thermal BEOL Bottleneck with Scaffolding

Dennis Rich, Mehdi Ashegi, Subhasish Mitra et al. Expected March 2022.

Presentations N3XT Heterogeneous Integration: From Lab to Fab

Dennis Rich, Robert Radway, Subhasish Mitra et al. SystemX November Conference 2019

Controlling Phase Change: Drying-Up Under Water or Staying Wet During Boiling

Paul Jones, Adrian Kirn, Dennis Rich, Ashley Elliot, Neelesh Patankar. Bull. Am. Phys. Soc. (2014) 59